

Data sheet acquired from Harris Semiconductor

CD74AC10, CD74ACT10

**Triple 3-Input NAND Gate** 

#### September 1998

### **Features**

- Typical Propagation Delay
  - 6ns at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ ,  $C_L = 50pF$
- Exceeds 2kV ESD Protection MIL-STD-883, Method 3015
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption
- Balanced Propagation Delays
- AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
- ±24mA Output Drive Current
  - Fanout to 15 FAST™ ICs
  - Drives  $50\Omega$  Transmission Lines

# Description

The CD74AC10 and CD74ACT10 are triple 3-input NAND gates that utilize the Harris Advanced CMOS Logic technology.

# **Ordering Information**

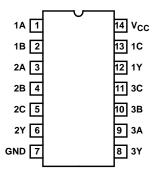
PART NUMBER	TEMP. RANGE ( <sup>o</sup> C)	PACKAGE	PKG. NO.
CD74AC10E	-55 to 125	14 Ld PDIP	E14.3
CD74ACT10E	-55 to 125	14 Ld PDIP	E14.3
CD74AC10M	-55 to 125	14 Ld SOIC	M14.15
CD74ACT10M	-55 to 125	14 Ld SOIC	M14.15

#### NOTES:

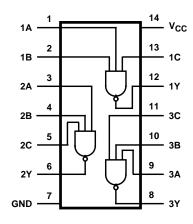
- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- Wafer and die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

## Pinout

CD74AC10, CD74ACT10 (PDIP, SOIC) TOP VIEW



# Functional Diagram



### **TRUTH TABLE**

	INPUTS						
nA	nB	nC	nY				
L	L	L	Н				
L	L	Н	Н				
L	Н	L	Н				
L	Н	Н	Н				
Н	L	L	Н				
Н	L	Н	Н				
Н	Н	L	Н				
Н	Н	Н	L				

# CD74AC10, CD74ACT10

## **Absolute Maximum Ratings**

DC Supply Voltage, V <sub>CC</sub> 0.5V to 6V
DC Input Diode Current, I <sub>IK</sub>
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$
DC Output Diode Current, I <sub>OK</sub>
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ ±50mA
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ (Note 3) $\pm 100$ mA

### **Thermal Information**

Thermal Resistance (Typical, Note 5)	$\theta_{JA}$ (oC/W)
PDIP Package	. 90
SOIC Package	. 175
Maximum Junction Temperature (Plastic Package)	150 <sup>0</sup> C
Maximum Storage Temperature Range	65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300°C

# **Operating Conditions**

Temperature Range, T <sub>A</sub>	125 <sup>0</sup> C
Supply Voltage Range, V <sub>CC</sub> (Note 4)	
AC Types	ว 5.5V
ACT Types4.5V to	5.5V
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub>	o V <sub>CC</sub>
Input Rise and Fall Slew Rate, dt/dv	
AC Types, 1.5V to 3V 50ns	(Max)
AC Types, 3.6V to 5.5V	(Max)
ACT Types, 4.5V to 5.5V	(Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTES:

- 3. For up to 4 outputs per device, add  $\pm 25 \text{mA}$  for each additional output.
- 4. Unless otherwise specified, all voltages are referenced to ground.
- 5.  $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

## **DC Electrical Specifications**

		1	ST ITIONS	v <sub>cc</sub>	25°C		-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	(V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
AC TYPES											
High Level Input Voltage	V <sub>IH</sub>	-	-	1.5	1.2	-	1.2	-	1.2	-	V
				3	2.1	-	2.1	-	2.1	-	V
				5.5	3.85	-	3.85	-	3.85	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	1.5	-	0.3	-	0.3	-	0.3	V
				3	-	0.9	-	0.9	-	0.9	V
				5.5	-	1.65	-	1.65	-	1.65	V
High Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	3	2.58	-	2.48	-	2.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V

# CD74AC10, CD74ACT10

# DC Electrical Specifications (Continued)

	_		ST ITIONS	v <sub>cc</sub>	25	o°C	-40°C TO 85°C			C TO 5°C	
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	(V)			MIN	MAX	MIN	MAX	UNITS
Low Level Output Voltage	$V_{OL}$	V <sub>IH</sub> or V <sub>IL</sub>	0.05	1.5	-	0.1	-	0.1	-	0.1	٧
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	lı	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	μΑ
Quiescent Supply Current, SSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	4	-	40	-	80	μΑ
ACT TYPES											
High Level Input Voltage	$V_{IH}$	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75	5.5	-	-	3.85	-	-	-	V
			-50	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	lį	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	μА
Quiescent Supply Current, SSI	Icc	V <sub>CC</sub> or GND	0	5.5	-	4	-	40	-	80	μΑ
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	Δl <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

### NOTES:

- 6. Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
- 7. Test verifies a minimum  $50\Omega$  transmission-line-drive capability at  $85^{\circ}$ C,  $75\Omega$  at  $125^{\circ}$ C.

# **ACT Input Load Table**

INPUT	UNIT LOAD
All	0.19

NOTE: Unit load is  $\Delta I_{CC}$  limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

# CD74AC10, CD74ACT10

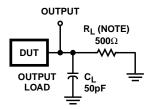
## **Switching Specifications** Input $t_r$ , $t_f = 3$ ns, $C_L = 50$ pF (Worst Case)

			-40°C TO 85°C			-55	5°C		
PARAMETER	SYMBOL	V <sub>CC</sub> (V)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
AC TYPES					•				
Propagation Delay, Input to	t <sub>PLH</sub> , t <sub>PHL</sub>	1.5	-	-	139	-	-	153	ns
Output		3.3 (Note 9)	4.4	-	15.5	4.3	-	17.1	ns
		5 (Note 10)	3.1	-	11.1	3.1	-	12.2	ns
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C <sub>PD</sub> (Note 11)	-	-	50	-	-	50	-	pF
ACT TYPES				•	•			•	
Propagation Delay, Input to Output	t <sub>PHL</sub>	5 (Note 10)	3.5	-	12.3	3.4	-	13.5	ns
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C <sub>PD</sub> (Note 11)	-	-	50	-	-	50	-	pF

#### NOTES:

- 8. Limits tested at 100%.
- 9. 3.3V Min at 3.6V, Max at 3V.
- 10. 5V Min at 5.5V, Max at 4.5V.

11.  $C_{PD}$  is used to determine the dynamic power consumption per gate. AC:  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ ACT:  $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$  where  $f_i$  = input frequency,  $C_L$  = output load capacitance,  $V_{CC}$  = supply voltage.



NOTE: For AC Series Only: When  $V_{CC}$  = 1.5V,  $R_L$  = 1k $\Omega$ .

	CD74AC	CD74ACT
Input Level	V <sub>CC</sub>	3V
Input Switching Voltage, V <sub>S</sub>	0.5 V <sub>CC</sub>	1.5V
Output Switching Voltage, V <sub>S</sub>	0.5 V <sub>CC</sub>	0.5 V <sub>CC</sub>

FIGURE 1. PROPAGATION DELAY TIMES

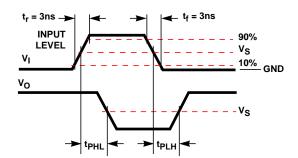


FIGURE 2. PROPAGATION DELAY TIMES

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